

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

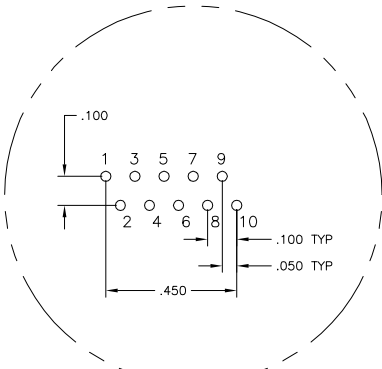
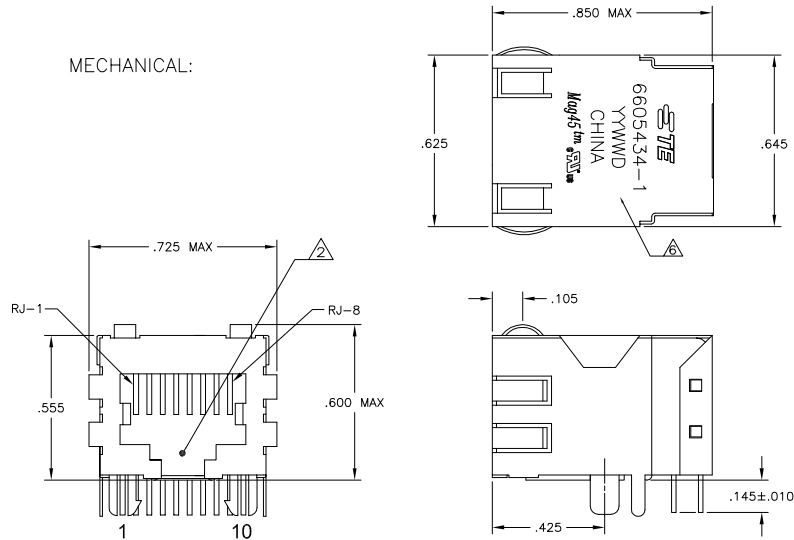
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LOC	QTY	REVISIONS	DATE	BY	APP
AA	22				
B		REV PER ECO-08-026413	08SEP2008	VL	TX
C		ECO-11-015766	30MAY2011	EL	LR

MECHANICAL:



Pin Designations

MATERIALS:
 HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0. SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER. MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE SOLDERDETAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.

RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.

MAGNETICS
 -IMPEDANCE: 100 OHMS
 -TURNS RATIO (CHIP-CABLE): 1:1 ALL FOUR PAIRS
 -OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, ALL FOUR PAIRS
 -ALL FOUR PAIRS BI-DIRECTIONAL
 -PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 4.0MHz
 12-20LOG(f/80)dB MIN FROM 4.01MHz TO 100MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 4.0MHz
 33-20*LOG(f/50)dB MIN FROM 4.01MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.

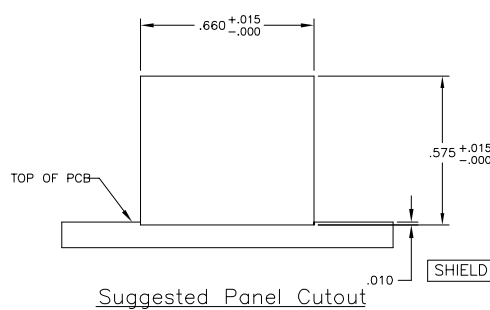
4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.

THE MAGNETICS ARE SYMMETRIC TO SUPPORT AUTO-MDI/MDIX.

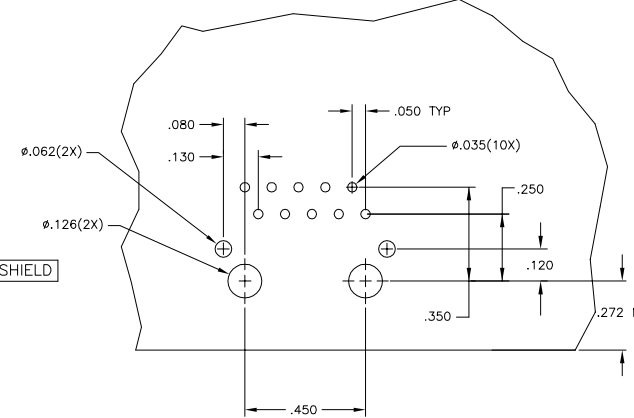
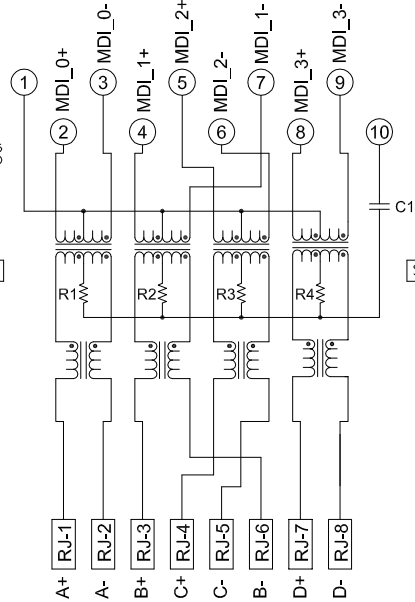
TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION AS SHOWN.

7. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

4G01 GIGABIT MAGNETIC CIRCUIT



Suggested Panel Cutout



Suggested PCB Layout (Component Side)

C1 = 1000 pF, 2kV CAPACITOR
 R1-R4 = 75 OHMS, 1/16W RESISTORS

YES	6605434-1
2KV DECOUPLING CAPACITOR	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV. ATTADIA - DIMARIS		REV. FAROLE - DIMARIS	
DIMENSIONS:	INCHES	REV. FAROLE	DATE	REV. FAROLE	DATE
0 P.C.	± .010	1	108-2100	1	108-2100
1 P.C.	± .010	2		2	
2 P.C.	± .010	3		3	
3 P.C.	± .010	4		4	
4 P.C.	± .010				
MATERIAL	FINISH	WEIGHT	SCALE	SHEET	REV
			NTS	1	C

TE Connectivity

1X1 MAG45(TM), MODULAR JACK (10 PIN HORIZ), 4G1 SCHEMATIC, 4G01 GIGABIT CIRCUIT, SHIELDED, OPTIONAL DECOUPLING CAPACITOR, NO LEADS

SIZE: 108-2100

CUSTOMER DRAWING